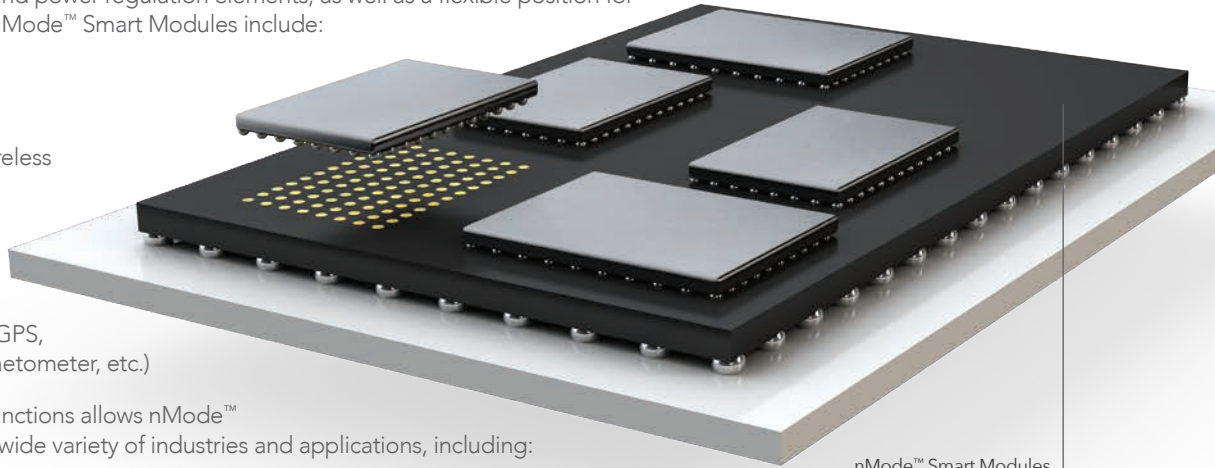


nMode™ SMART MODULES

CUSTOMIZABLE IC PACKAGE DESIGNS FOR HIGH-PERFORMANCE, HIGH-DENSITY APPLICATIONS

Samtec's new line of organic and silicon-based nMode™ Smart Modules, RF Filters and Evaluation Boards is designed to support the high-performance, high-density demands of the IC packaging industry. Smart Modules are available with central control or compute, wireless, antenna and power regulation elements, as well as a flexible position for functionality customization. nMode™ Smart Modules include:

- Micro controller
- Antenna
- Bluetooth® short-range wireless communication
- Power regulator
- Customizable position for application-specific sensor requirements (e.g. GPS, accelerometer, gyro, magnetometer, etc.)



The flexibility to customize functions allows nMode™ Smart Modules to support a wide variety of industries and applications, including:

- Industrial tracking and data collection
- Smart tool diagnostics
- Orthopedic rehabilitation and recovery
- Distributed agriculture applications
- Animal health monitoring
- Wearable technology
- Medical external monitoring
- Automotive monitoring and tracking

nMode™ Smart Modules incorporate central control or compute, wireless communication, antenna and power regulation elements, as well as the flexibility to add application-specific sensor dies.

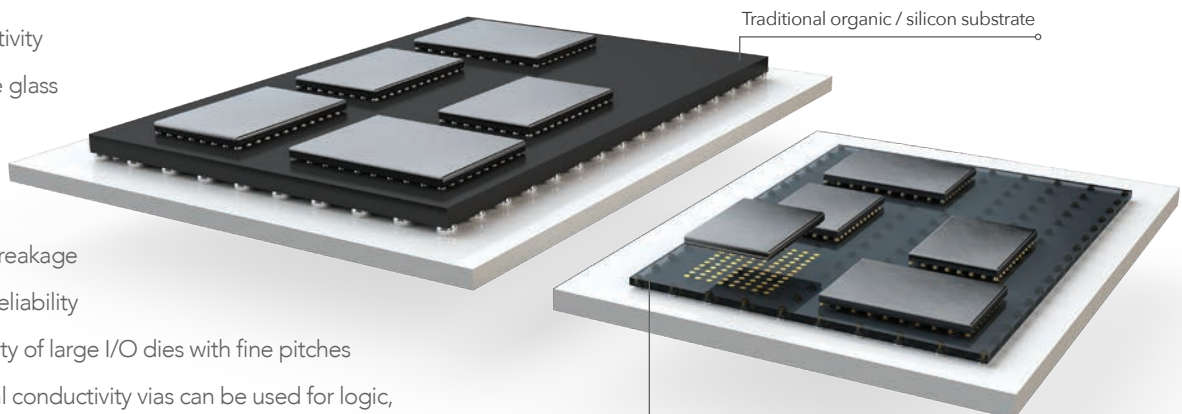
To discuss your application requirements, please contact Samtec Microelectronics at sme@samtec.com.

NEXT GENERATION IC PACKAGING

GLASS INTERPOSERS ENABLE NEW LEVEL OF MINIATURIZATION & INTEGRATION FOR SMART MODULES

Samtec's new Glass Core Technology leverages the superior performance and material characteristics of glass interposers to provide ultra high-performance solutions for next generation system demands. Benefits include:

- Electrical conductivity
- TCE match to the glass
- Low warp
- Hermetic Cu-based vias
- Reduced wafer breakage
- Thermal cycling reliability
- Increased reliability of large I/O dies with fine pitches
- Improved thermal conductivity vias can be used for logic, power or other applications where thermal management is critical



Samtec's Glass Core Technology enables up to 30% reduction in size along with numerous performance benefits

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